

METHODS AND SYSTEMS FOR PROVIDING
MEMS DEVICES WITH A TOP CAP AND UPPER
SENSE PLATE

ABSTRACT OF THE DISCLOSURE

5 A method for fabricating a MEMS device having a top cap and an upper sense plate is described. The method includes producing a device wafer including an etched substrate, etched MEMS device components, and interconnect metal, a portion of the interconnect metal being bond pads and adding a metal wraparound layer to a back side, edges, and a portion of a front side of the device wafer. The method also includes producing an upper wafer including an etched substrate and interconnect metal, bonding the device wafer and the upper wafer, and dicing the bonded upper wafer and device wafer into individual MEMS devices.